# 2309410-1 ✓ ACTIVE

DDR4 DIMM

TE Internal #: 2309410-1

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board, DDR4 DIMM

View on TE.com >

Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM SOCKETS

DRAM Type: **Small Outline (SO)**

Stack Height: **5.2 mm [ .205 in ]**

Module Orientation: **Right Angle**

PCB Mounting Style: **Surface Mount**

Connector System: **Cable-to-Board**

All DDR4 SO DIMM SOCKETS (39)

## Features

### Product Type Features

| | |
|---|---|
| Center Post | Without |
| DRAM Type | Small Outline (SO) |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |

### Configuration Features

| | |
|---|---|
| Center Key | Offset Right |
| Number of Keys | 1 |
| Module Orientation | Right Angle |
| Number of Positions | 200, 260 |
| Number of Rows | 2 |
| Keying | Reverse |

### Electrical Characteristics

| | |
|---|---|
| DRAM Voltage | 1.2 V |

### Signal Characteristics

| | |
|---|---|
| SGRAM Voltage | 1.2 V |

## Body Features

| | |
|---|---|
| Retention Post Material | Copper Alloy |
| Ejector Location | Both Ends |
| Latch Material | High Temperature Thermoplastic |
| Retention Post Location | Both Ends |
| Ejector Type | Locking |
| Connector Profile | Low |

## Contact Features

| | |
|---|---|
| Socket Style | SO DIMM |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Current Rating (Max) | .5 A |
| Socket Type | Memory Card |

## Termination Features

| | |
|---|---|
| Insertion Style | Cam-In |

## Mechanical Attachment

| | |
|---|---|
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |

## Housing Features

| | |
|---|---|
| Centerline (Pitch) | .5 mm, 3.3 mm[.02 in][.129 in] |
| Housing Color | Black |
| Housing Material | High Temperature Thermoplastic |

## Dimensions

| | |
|---|---|
| Stack Height | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |

## Usage Conditions

| | |
|---|---|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |

### Operation/Application

| | |
|---|---|
| Circuit Application | Power |

### Industry Standards

| | |
|---|---|
| UL Flammability Rating | UL 94V-0 |

### Packaging Features

| | |
|---|---|
| Packaging Method | Tape & Reel |
| Packaging Quantity | 800 |

## Product Compliance

For compliance documentation, visit the product page on TE.com>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224)<br>Candidate List Declared Against: JUL 2021 (219)<br>SVHC > Threshold:<br>Not Yet Reviewed |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## Compatible Parts

TE Part # 2309414-2

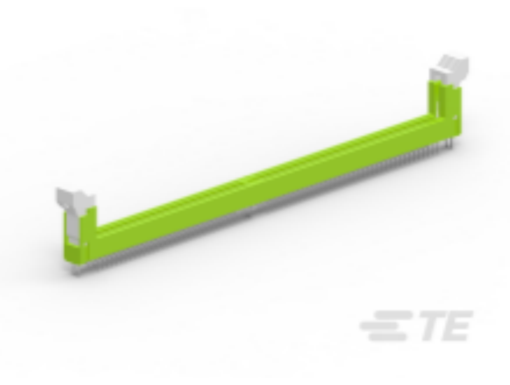
DDR4 SODIMM 260P 9.2H RVS

## Also in the Series | DDR4 DIMM

DIMM Sockets(69)

SO DIMM Sockets(39)

## Customers Also Bought



TE Part #2308107-3

DDR4 DIMM 288 PIN TH TYPE

TE Part #2309407-1

DDR4 SO DIMM SOCKETS

TE Part #2-2013289-1

EMBOSS TAPE DDR3 204P 5.2H STD

TE Part #1734035-4

MINI USB, TYPE B, R/A, SMT, MYLAR

TE Part #3-2176382-2

RQ 0805 280K 0.1% 10PPM 5K RL

TE Part #1-1419129-8

OJ-SS-112DM,000

TE Part #174552-1

4P C-MNL PIN HDR R/A

## Documents

### Product Drawings

DDR4 SODIMM 260P 5.2H RVS

English

### CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309410-1_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309410-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309410-1_1.3d_stp.zip

English

## Product Specifications

Application Specification

English

## Product Environmental Compliance

Product Compliance

English

Product Compliance

English